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Global Molybdenum Copper Electronic Packaging Material Supply, Demand and Key Producers, 2026-2032

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Abstracts

The global Molybdenum Copper Electronic Packaging Material market size is expected to reach $ 1391 million by 2032, rising at a market growth of 5.5% CAGR during the forecast period (2026-2032).

Molybdenum copper electronic packaging material is a functional composite material based on molybdenum (Mo) and copper (Cu) as basic elements. By adjusting the composition ratio and processing technology, it achieves adjustable coefficient of thermal expansion (CTE), high thermal conductivity, excellent mechanical strength and other characteristics. It is widely used in electronic packaging scenarios such as high-frequency communication and power devices. The core types of molybdenum copper electronic packaging materials are mainly divided into two categories based on structural and functional differences:

Layered composite type: a sandwich structure represented by copper molybdenum copper (Cu/Mo/Cu), with a middle layer of molybdenum or molybdenum copper alloy (thickness accounting for 30% -50%) and an outer layer of high-purity copper. Its thermal conductivity can reach 240-280 W/m · K, and its CTE can be adjusted to 6.5-8.5 ? 10 ??/K. It has excellent compatibility with silicon chips (4-7 ? 10 ??/K) and can effectively reduce the risk of interface failure caused by thermal stress.

Dispersion composite type: Molybdenum powder and copper powder are mixed and sintered using powder metallurgy technology to form a uniformly distributed biphasic structure. The material has a density of 9.5-10.2 g/cm ? and combines high tensile strength (? 400 MPa) and conductivity (? 45% IACS), making it suitable for packaging substrates in high vibration environments.

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Outstanding thermal management efficiency: The thermal conductivity of molybdenum copper alloy (240-300 W/m · K) is significantly higher than that of traditional packaging materials (such as 170-200 W/m · K of aluminum silicon carbide), which can reduce the temperature rise of power devices by 15% -20% and extend their service life. High process adaptability: Foil or sheet materials with a thickness of 0.05-3 mm can be prepared through rolling composite technology, with a surface roughness (Ra) of ? 0.8 ? m. It supports precision processing such as laser cutting and chemical etching, and is suitable for high-density integrated circuit packaging requirements. Strong environmental reliability: Molybdenum has a melting point of 2620 ° C and can withstand working temperatures of 300-500 ° C for a long time in high-temperature packaging scenarios without oxidation or volatilization issues, ensuring the airtightness of the packaging.

The industrial production of molybdenum copper electronic packaging materials mainly relies on two types of technologies:

Rolling composite process: Molybdenum plate and copper foil are metallurgically bonded by hot rolling (temperature 800-950 ° C), with an interface shear strength of ? 80 MPa. The production efficiency is 30% -50% higher than powder metallurgy method, and it is suitable for continuous production of large-sized (? 600 mm wide) plates.

Copper infiltration sintering process: Using molybdenum powder as the matrix (particle size 1-5 ? m), after isostatic pressing, high-temperature copper infiltration (1350-1450 ° C) is carried out. The finished product has a density of ? 98% and a porosity of no more than 1%, which can prepare structural components with complex and irregular shapes.

Molybdenum copper electronic packaging materials have been widely applied in the following fields:

High frequency communication module: In 5G base station RF devices, its low CTE characteristics can reduce signal transmission delay by 10% -15%, and at the same time, through high thermal conductivity design, the junction temperature of the power amplifier chip is controlled within 85 ° C.

Power semiconductor packaging: used as an insulating substrate for IGBT modules, with a thermal resistance of ? 0.15 ° C · cm ?/W, supporting current density increase to over 200 A/cm ?, meeting the requirements of new energy vehicle electronic control systems.

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Optoelectronic device heat dissipation: In laser diode packaging, the heat dissipation module containing molybdenum copper carrier can improve the stability of optical power output to ± 1.5%, which is suitable for data center optical communication equipment. In 2025, global Molybdenum Copper Electronic Packaging Material production reached approximately 6,800 MT, with an average global market price of around US$ 137 per kg.

The annual production capacity of molybdenum copper electronic packaging materials is 10,000 tons, with a gross profit margin of about 30%.

Upstream: Molybdenum powder; Electrolytic copper or high-purity copper; Powder metallurgy materials; High purity metal materials.

Downstream: high-frequency communication module, power semiconductor packaging, optoelectronic device heat dissipation.

The cost of raw materials is about 55%; The manufacturing and processing cost is about 25%; The cost of equipment and energy consumption is about 10%; The labor and management costs are about 5%; The cost of surface treatment and testing is about 5%.

This report studies the global Molybdenum Copper Electronic Packaging Material production, demand, key manufacturers, and key regions.

This report is a detailed and comprehensive analysis of the world market for Molybdenum Copper Electronic Packaging Material and provides market size (US$ million) and Year-over-Year (YoY) Growth, considering 2025 as the base year. This report explores demand trends and competition, as well as details the characteristics of Molybdenum Copper Electronic Packaging Material that contribute to its increasing demand across many markets.

Highlights and key features of the study

Global Molybdenum Copper Electronic Packaging Material total production and demand, 2021-2032, (Tons)

Global Molybdenum Copper Electronic Packaging Material total production value, 2021-2032, (USD Million)

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Global Molybdenum Copper Electronic Packaging Material production by region & country, production, value, CAGR, 2021-2032, (USD Million) & (Tons), (based on production site)

Global Molybdenum Copper Electronic Packaging Material consumption by region & country, CAGR, 2021-2032 & (Tons)

U.S. VS China: Molybdenum Copper Electronic Packaging Material domestic production, consumption, key domestic manufacturers and share

Global Molybdenum Copper Electronic Packaging Material production by manufacturer, production, price, value and market share 2021-2026, (USD Million) & (Tons)

Global Molybdenum Copper Electronic Packaging Material production by Type, production, value, CAGR, 2021-2032, (USD Million) & (Tons)

Global Molybdenum Copper Electronic Packaging Material production by Application, production, value, CAGR, 2021-2032, (USD Million) & (Tons)

This report profiles key players in the global Molybdenum Copper Electronic Packaging Material market based on the following parameters - company overview, production, value, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include ALMT Corp, AMETEK, H.C. Starck Hermsdorf GmbH, Negele Hartmetall-Technik GmbH, Santier, ATT Advanced Elemental Materials, Changzhou Fuxi Technology, Changsha Saneway Electronic Materials, Luoyang Combat Tungsten & Molybdenum Materials, Shaanxi Puwei Electronic Technology, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Stakeholders would have ease in decision-making through various strategy matrices used in analyzing the World Molybdenum Copper Electronic Packaging Material market

Detailed Segmentation:

Each section contains quantitative market data including market by value (US$ Millions), volume (production, consumption) & (Tons) and average price (US$/Ton) by

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manufacturer, by Type, and by Application. Data is given for the years 2021-2032 by year with 2025 as the base year, 2026 as the estimate year, and 2027-2032 as the forecast year.

Global Molybdenum Copper Electronic Packaging Material Market, By Region:

United States

China

Europe

Japan

South Korea

ASEAN

India

Rest of World

Global Molybdenum Copper Electronic Packaging Material Market, Segmentation by Type:

Mo60Cu40

Mo75Cu25

Mo80Cu20

Mo85Cu15

Other

Global Molybdenum Copper Electronic Packaging Material Market, Segmentation by Structure:

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Layered Composite Type

Dispersed Composite Type

Global Molybdenum Copper Electronic Packaging Material Market, Segmentation by Preparation Process:

Rolling Composite Process?

Copper Infiltration Sintering Process?

Global Molybdenum Copper Electronic Packaging Material Market, Segmentation by Application:

High Frequency Communication Module

Power Semiconductor Packaging

Heat Dissipation Of Optoelectronic Devices

Other

Companies Profiled:

ALMT Corp

AMETEK

H.C. Starck Hermsdorf GmbH

Negele Hartmetall-Technik GmbH

Santier

ATT Advanced Elemental Materials

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Changzhou Fuxi Technology

Changsha Saneway Electronic Materials

Luoyang Combat Tungsten & Molybdenum Materials

Shaanxi Puwei Electronic Technology

ATTL Advanced Materials

Starshining Advanced Materials

Key Questions Answered:

1. How big is the global Molybdenum Copper Electronic Packaging Material market?
2. What is the demand of the global Molybdenum Copper Electronic Packaging Material market?
3. What is the year over year growth of the global Molybdenum Copper Electronic Packaging Material market?
4. What is the production and production value of the global Molybdenum Copper Electronic Packaging Material market?
5. Who are the key producers in the global Molybdenum Copper Electronic Packaging Material market?
6. What are the growth factors driving the market demand?

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